

DDR4 DIMM

TE Internal #: 2199154-3

TE Internal Description: DDR4 DIMM 288 Pin TH type

DDR4 DIMM SOCKETS

[View on TE.com >](#)



Connectors > Socket Connectors > Memory Sockets > DIMM Sockets > DDR4 DIMM SOCKETS



DRAM Type: Double Data Rate (DDR) 4

Connector System: Board-to-Board

Number of Positions: 288

Termination Method to PCB: Through Hole - Solder

Module Orientation: Vertical

[All DDR4 DIMM SOCKETS \(25\)](#)

Features

Electrical Characteristics

DRAM Voltage	1.2 V
--------------	-------

Operation/Application

Circuit Application	Signal
---------------------	--------

Industry Standards

UL Flammability Rating	UL 94V-0
------------------------	----------

Mechanical Attachment

Connector Mounting Type	Board Mount
PCB Mount Retention	With
Mount Angle	Vertical
PCB Mount Retention Type	Boardlock
Mating Alignment Type	Offset Right
Mating Alignment	With

Contact Features

Contact Underplating Material	Nickel
Socket Style	DIMM
Contact Mating Area Plating Material Thickness	.38 μm[15 μin]



PCB Contact Termination Area Plating Material Thickness	3 μm[118.1 μin]
Contact Mating Area Plating Material	Gold
Memory Socket Type	Memory Card
Contact Base Material	Copper Alloy
PCB Contact Termination Area Plating Material	Tin
Contact Current Rating (Max)	.75 A

Packaging Features

Packaging Quantity	80
Packaging Method	Tray, Box & Tray

Body Features

Retention Post Location	None
Latch Color	Black
Latch Material	High Temperature Thermoplastic
PCB Retention Feature Material	Stainless Steel
Ejector Material Color	Black
Module Key Type	Offset Right
Ejector Location	Both Ends
Ejector Material	High Temperature Thermoplastic
Ejector Type	Standard

Dimensions

Center Retention Hole Diameter	1.2 mm[.047 in]
Profile Height from PCB	20 mm[.787 in]
Row-to-Row Spacing	2.2 mm[.08 in]

Housing Features

Housing Color	Black
Housing Material	High Temperature Nylon
Centerline (Pitch)	.85 mm[.033 in]

Termination Features

Insertion Style	Direct Insert
Termination Post & Tail Length	2.67 mm[.105 in]
Termination Method to PCB	Through Hole - Solder

Configuration Features

--	--



Number of Keys	1
Number of Bays	2
Number of Rows	2
Number of Positions	288
Module Orientation	Vertical

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
DRAM Type	Double Data Rate (DDR) 4
Connector System	Board-to-Board

Usage Conditions

Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
-----------------------------	----------------------------

Other

EU RoHS Compliance	Compliant
EU ELV Compliance	Compliant

Product Compliance

For compliance documentation, visit the product page on [TE.com](#)>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JAN 2021 (211) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Wave solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits



as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts

TE Part # 2-2822979-3
LGA3647-0 SOCKET P0 KIT FOR ODM (30U AU)

Also in the Series | DDR4 DIMM

DIMM Sockets(25)

SO DIMM Sockets(39)

Customers Also Bought

TE Part #880584-2
SHUNT CONNECTOR

TE Part #1-1761186-1
4 SDL SE O-S RCPT ASSY

TE Part #5-1761186-1
4 SDL SE O-S RCPT ASSY

TE Part #7-2199154-9
DDR4 DIMM 288 PIN TH TYPE

TE Part #1892801-4
MBXL VERT HDR 16S+2p

TE Part #3-6450840-5
MBXLE R/A HEADER 1P+24S+1P

TE Part #1926024-4
cpmm. skt w/latch, smt,mc-p5s1

TE Part #6469602-3
3.43 MM CONTACT TAIL LENGTH DUAC

Documents



Product Drawings

DDR4 DIMM 288 Pin TH type

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2199154-3_C5.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2199154-3_C5.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2199154-3_C5.3d_stp.zip

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

DDR4 DIMM Socket Flyer (English)

English

DDR4 DIMM Socket Flyer (Chinese)

Product Specifications

Product Specification

English

Product Specification

English